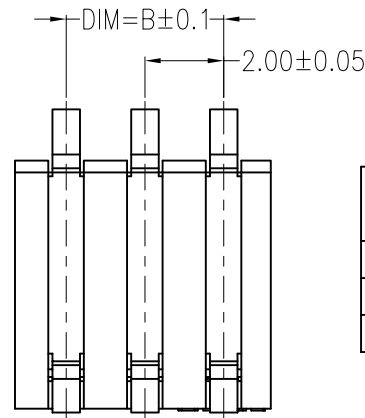
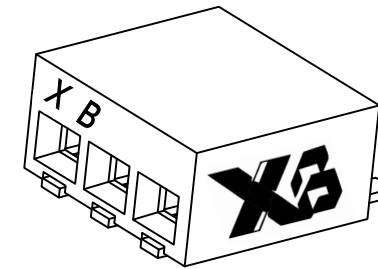
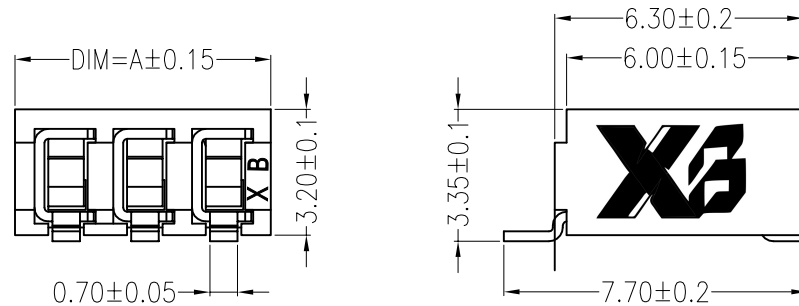
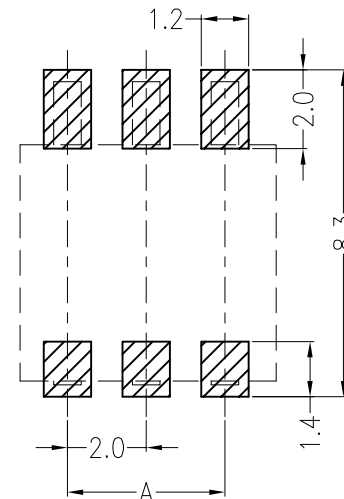


REV	DESCRIPTION	DESIGN	DATE
A0	Release	吴丹平	2016.04.30



Circuit	Dimensions (mm)	
	DIM=A	DIM=B
L023Y-01	2.50	
L023Y-02	4.50	2.00
L023Y-03	6.50	4.00



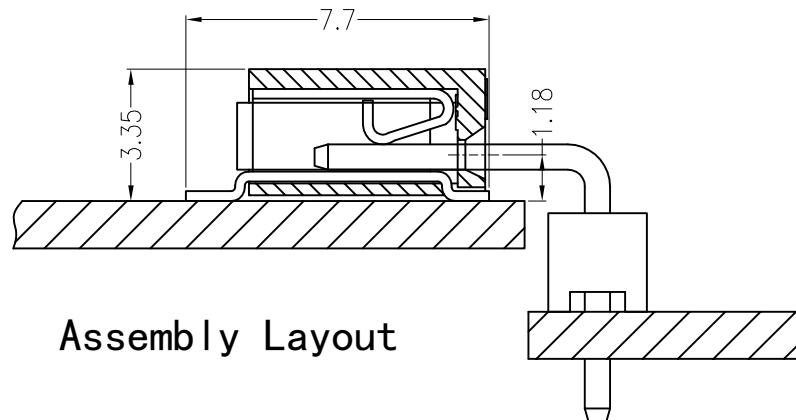
Board Layout

主要技术参数 Main Specifications

线 数 (Poles): 01 to 03
 接触电阻 (Contact resistance): $\leq 20\text{m}\Omega$
 绝缘电阻 (Insulation resistance): $\geq 1000\text{M}\Omega$
 额定电压 (Rated voltage): 125V AC DC
 额定电流 (Rated current): 1.0A AC DC
 耐 电 压 (Withstand Voltage): 1000V AC/minute
 温度范围 (Temperature Range): $-25^{\circ}\text{C} \sim +105^{\circ}\text{C}$

ORDER INFORMATION:

XB-L023Y-**-F2MB-P			
PART No.		PACKAGING:	
No. FOR CIRCUITS:		P=PE	
01~03		R=REEL	
PLASTIC MATERIAL:		PLATING:	
F2M=LCP (BEIGE)		B=MATTE Sn	



Assembly Layout

ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
C				
B	CONTACT	1~3 PCS	PhosphorBronze	MATTE Sn-plated
A	PEDESTAL	1 PCS	LCP	UL 94V-0, COLOR:BEIGE
东莞市溪榜电子有限公司				
DONG GUAN XI BANG ELECTRONICS CO., LTD				
X.±0.5	X.±5°	USE:	CUSTOMER	
.X±0.3	.X±2°	APPD:	邵敬和	
.XX±0.25	.XX±1°	CHKD:	田峰	
--	--	DR:	周秀龙	
⊕	⊖	UNITS: mm	SCALE	SHEET
			1 : 1	1 / 1

TITLE: -
2.0mmPITCH 90°WAFER SMT TYPE

PART NO.:
L023Y-**-F2MB-R

DWG NO.: